

IN THE SPECIFICATION:

Please amend the paragraphs at page 8, line 23 – page 9, line 12 with the following amended paragraphs:

Fig. 4 is a stereographic diagram viewing from the inner surface 1402 of the lower metal shell 14 of Fig. 1. The lower metal shell 14 has several stakes 32 and a bent extension 24 34, and the surface 1402 is covered with an insulator film for insulation, preferably a Polytetrafluoroethylene material such as Teflon.

Fig. 5 is a stereographic diagram viewing from the lower half case 24 of Fig. 1. The inner surface 1402 of the lower metal shell 14 is coated with an insulator film. The plastic frame 18 has I/O portion 20, and injection molding technique is used to embed the bent extension 24 34 into the I/O portion 20, with the plastic frame 18 embedding the stake 28 32. I/O portion 20 has a plastic frame 2002 and holes 2004 to expose the copper of the transmission ports of the printer circuit board inside the small memory card 10.

Please amend the paragraph at page 11, line 25 – page 12, line 7 with the following amended paragraph:

Fig. 14 is to cut the connection bars 34 108 and 36 110 between the metal shell 12 and metal belt 100 by stamping to release the upper half case

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22 from the metal belt 100 and at the same time to form the recesses 26 and 28. This step is to unload the semi-finished products. The lower half-case 24 is formed by the same process as in the aforementioned description. In the last step 208 is sonic welding the upper and lower half cases 22 and 24 together to form the small memory card 10.